SOT27-1

plastic dual in-line package; 14 leads (300 mil)

8 February 2016 Package information

1. Package summary

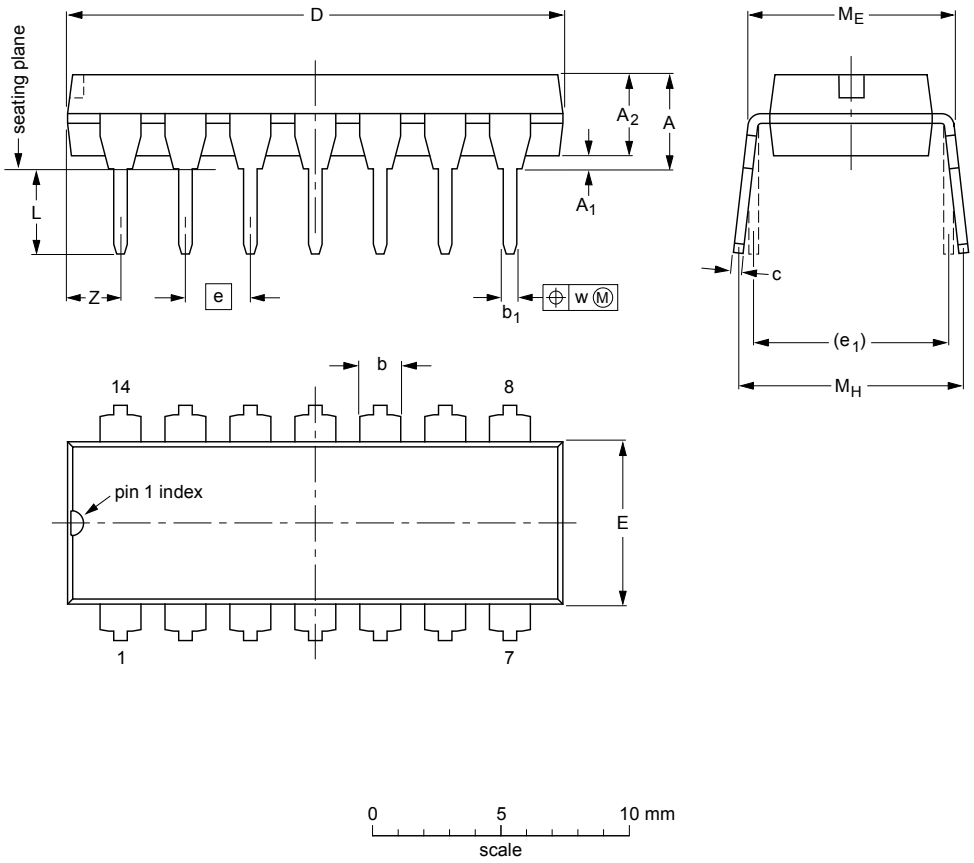
Terminal position code	D (double)
Package type descriptive code	DIP14
Package type industry code	DIP14
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	050G04
JEDEC package outline code	MO-001
JEITA package outline code	SC-501-14
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		18.55	-	19	19.5	mm
E	package width		6.2	-	6.35	6.48	mm
A	seated height		[tbd]	-	4.2	4.2	mm
A_2	package height		[tbd]	-	3.04	3.2	mm
n_2	actual quantity of termination		-	-	14	-	

2. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil) **SOT27-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.02	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.1	0.3	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT27-1	050G04	MO-001	SC-501-14			~~99-12-27~~ 03-02-13

Fig. 1. Package outline DIP14 (SOT27-1)

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